

ABSTRACT OF THE DISCLOSURE

A processing apparatus that solves a problem of the wasteful preparing of two laser processing apparatuses, of which wavelengths are different. The processing apparatus
5 includes: a holding means that holds a wafer; laser beam applying unit that applies a pulsed laser beam onto the wafer held on the holding means; and process-feeding means that process-feeds the holding means and the laser beam applying unit relative to each other. The laser beam
10 applying unit includes: an oscillator that oscillates a pulsed laser beam; a splitting portion that splits the pulsed laser beam, oscillated by the oscillator, into a first optical path and a second optical path; a first condenser that is disposed on the first optical path and
15 condenses the pulsed laser beam onto the wafer held on the holding means; a wavelength converter that is disposed on the second optical path and converts a wavelength of the pulsed laser beam oscillated by the oscillator; and a second condenser that condenses a pulsed laser beam,
20 generated after the wavelength is converted, onto the wafer held on the holding means.

[FIG. 2]